



2 Pad Ceramic Package Quartz Crystal, 5 mm x 7 mm

ILCX10 Series

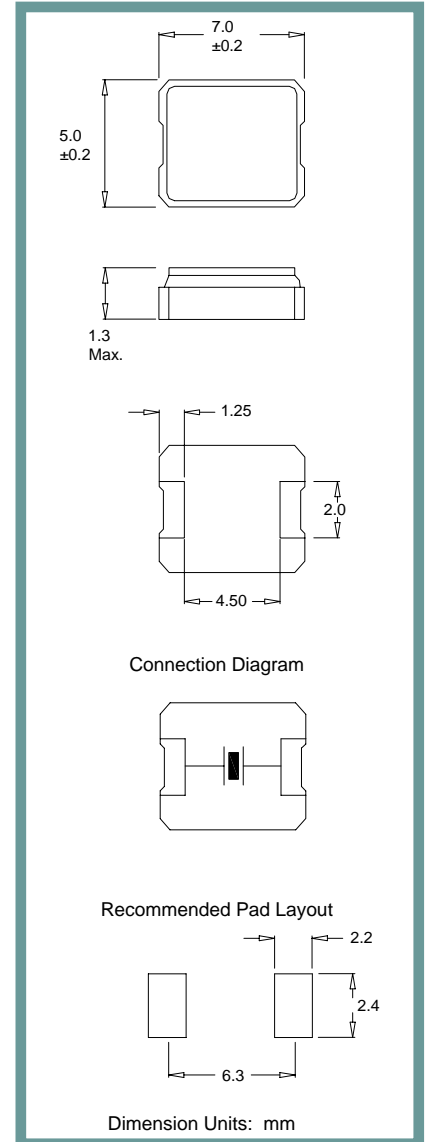
**Product Features:**

- Low Cost SMD Package
- Low ESR
- Compatible with Leadfree Processing

**Applications:**

- Fibre Channel
- Server & Storage
- Sonet /SDH
- 802.11 / Wifi
- T1/E1, T3/E3

<b>Frequency</b>	6 MHz to 100 MHz
<b>ESR (Equivalent Series Resistance)</b>	
6.0 MHz – 40.0 MHz	40 Ω Max.
36.0 MHz – 100.0 MHz (3 <sup>rd</sup> O.T.)	40 Ω Max.
<b>Shunt Capacitance (C0)</b>	7 pF Max.
<b>Frequency Tolerance @ 25° C</b>	±30 ppm Standard (see Part Number Guide for more options)
<b>Frequency Stability over Temperature</b>	±50 ppm Standard (see Part Number Guide for more options)
<b>Crystal Cut</b>	AT Cut
<b>Load Capacitance</b>	18 pF Standard
<b>Drive Level</b>	100 μW Max.
<b>Aging</b>	±5 ppm Max. / Year Standard
<b>Temperature</b>	
<b>Operating</b>	0° C to +70° C Standard (see Part Number Guide for more options)
<b>Storage</b>	-40° C to +85° C Standard

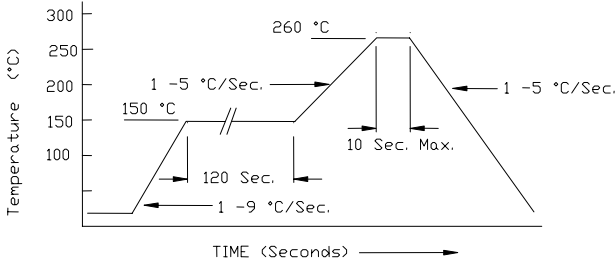


Part Number Guide		Sample Part Number: ILCX10 - FB1F18 - 20.000				
Package	Tolerance (ppm) at Room Temperature	Stability (ppm) over Operating Temperature	Operating Temperature Range	Mode (overtone)	Load Capacitance (pF)	Frequency
ILCX10 -	B = ±50 ppm	B = ±50 ppm	0 = 0°C to +50°C	F = Fundamental	18 pF Standard Or Specify	- 20.000 MHz
	F = ±30 ppm	F = ±30 ppm	1 = 0°C to +70°C	3 = 3 <sup>rd</sup> overtone		
	G = ±25 ppm	G = ±25 ppm	2 = -10°C to +60°C			
	H = ±20 ppm	H = ±20 ppm	3 = -20°C to +70°C			
	I = ±15 ppm	I = ±15 ppm**	5 = -40°C to +85°C			
J = ±10 ppm*	J = ±10 ppm**	9 = -10°C to +50°C				

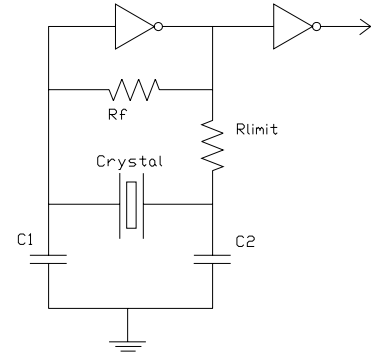
\* Not available at all frequencies. \*\* Not available for all temperature ranges.

**Pb Free Solder Reflow Profile:**

**Typical Circuit:**



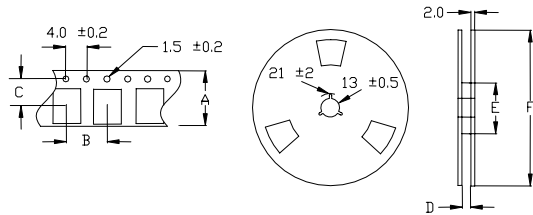
\*Units are backward compatible with 240C reflow processes



**Package Information:**

MSL = 1  
Termination = e4 (Au over Ni over W base metal).

**Tape and Reel Information:**



Quantity per Reel	1000
A	16 +/- .3
B	8 +/- .2
C	7.5 +/- .2
D	17.5 +/- .1
E	50 / 60 / 80
F	180 / 250

**Environmental Specifications**

Thermal Shock	MIL-STD-883, Method 1011, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A
Resistance to Soldering Heat	J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max)
Hazardous Substance	Pb-Free / RoHS / Green Compliant
Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Terminal Strength	MIL-STD-883, Method 2004, Test Condition D
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2, R1=2x10-8 atm cc/s
Solvent Resistance	MIL-STD-202, Method 215

**Marking**

Line 1: ILSI, Date Code (yww)  
Line 2: Frequency